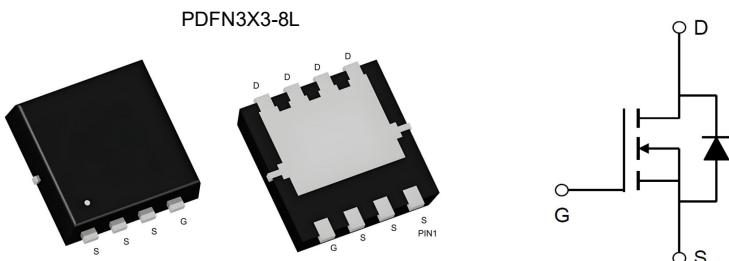


## N-Channel 100V(D-S) MOSFET

Product summary			Features
$V_{DS}$	100	V	<ul style="list-style-type: none"> <li>Advanced Split Gate Trench Technology</li> <li>Low <math>R_{DS(ON)}</math></li> </ul>
$R_{DS(ON)}$ (at $V_{GS}=10V$ ) Typ.	13	$m\Omega$	<b>Applications</b> <ul style="list-style-type: none"> <li>Load switching</li> <li>PWM Applications</li> <li>Power Management</li> </ul>
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ ) Typ.	16.5	$m\Omega$	
$I_D(T_C=25^\circ C)$	30	A	

### Pin Configuration



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAL30N10	PDFN3X3-8L	13 "	5000pcs

### Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C=25^\circ C$	A
		$T_C=100^\circ C$	A
$I_{DM}$	Pulse Drain Current Tested <sup>A</sup>	130	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>B</sup>	100	mJ
$P_D$	Power Dissipation $T_C=25^\circ C$	65	W
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to +150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JC}$	Thermal Resistance-Junction to case max	1.9	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance-Junction to ambient max <sup>C</sup>	50	$^\circ C/W$

Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{D}}=250\mu\text{A}$	100	--	--	V
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=60\text{V}, \text{V}_{\text{GS}}=0\text{V}$	--	--	1.0	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Body Leakage Current	$\text{V}_{\text{DS}}=0\text{V}, \text{V}_{\text{GS}}=\pm 20\text{V}$	--	--	$\pm 100$	nA
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.5	V
$\text{R}_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance <sup>D</sup>	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_{\text{D}}=20\text{A}$	--	13	17	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_{\text{D}}=10\text{A}$	--	16.5	22	$\text{m}\Omega$
$\text{V}_{\text{SD}}$	Diode Forward Voltage	$\text{I}_{\text{S}}=30\text{A}, \text{V}_{\text{GS}}=0\text{V}$	--	--	1.2	V
Dynamic Parameters <sup>E</sup>						
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=50\text{V}$ $f=1\text{MHz}$	--	1130	--	pF
$\text{C}_{\text{oss}}$	Output Capacitance		--	430	--	pF
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		--	5.8	--	pF
$\text{Q}_{\text{g}}$	Total Gate Charge	$\text{V}_{\text{DS}}=50\text{V}, \text{I}_{\text{D}}=10\text{A}$ $\text{V}_{\text{GS}}=0 \text{ to } 10\text{V}$	--	15	--	nC
$\text{Q}_{\text{gs}}$	Gate-Source Charge		--	4	--	nC
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		--	1.9	--	nC
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$\text{V}_{\text{DD}}=50\text{V}$ $, \text{R}_{\text{GEN}}=6\Omega$ , $\text{I}_{\text{D}}=10\text{A}$ , $\text{V}_{\text{GS}}=10\text{V}$	--	4.5	--	ns
$t_{\text{r}}$	Turn-on Rise Time		--	5.6	--	ns
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	16	--	ns
$t_{\text{f}}$	Turn-off Fall Time		--	9	--	ns
$t_{\text{rr}}$	Reverse recovery time	$\text{I}_{\text{F}}=15\text{A}$ , $d\text{i}/dt=100\text{A}/\mu\text{s}$	--	40	--	ns
$Q_{\text{rr}}$	Reverse recovery charge		--	32	--	nC

A. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

B. EAS condition:  $T_J=25^\circ\text{C}$ ,  $\text{V}_{\text{DD}}=50\text{V}$ ,  $\text{R}_{\text{G}}=25\Omega$ ,  $\text{V}_{\text{G}}=10\text{V}$ ,  $\text{L}=0.5\text{mH}$ ,  $\text{I}_{\text{AS}}=20\text{A}$ .

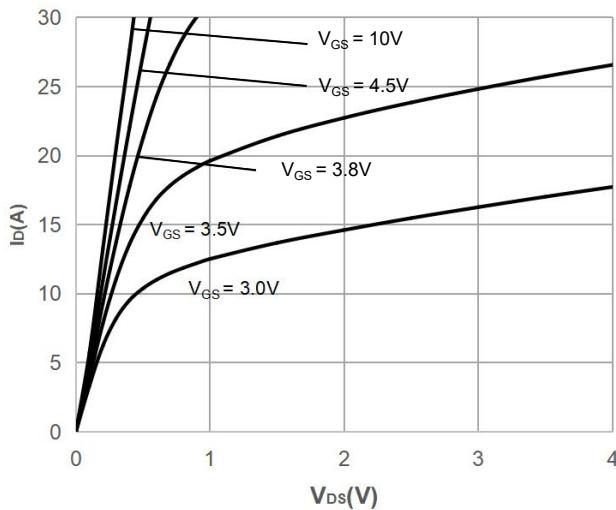
C. The data tested by surface mounted on a 1 inch x 1 inch FR-4 board with 2OZ copper.

D. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

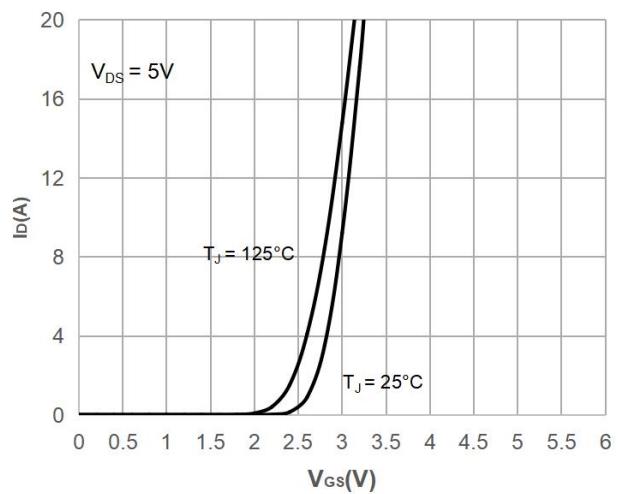
E. Guaranteed by design, not subject to production testing.

## Typical Characteristics

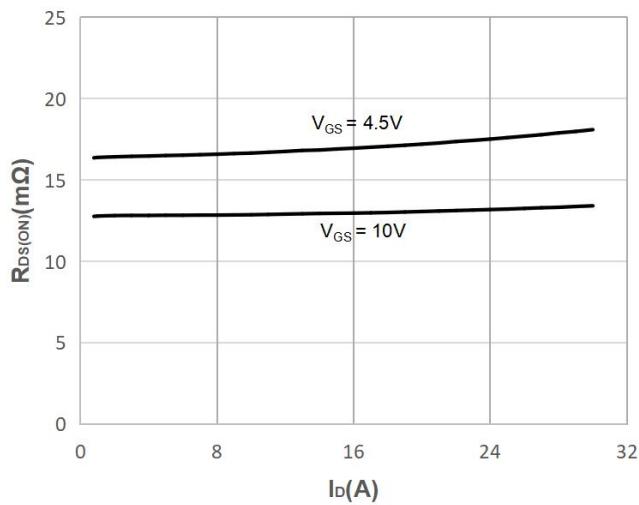
**Figure 1: Output Characteristics**



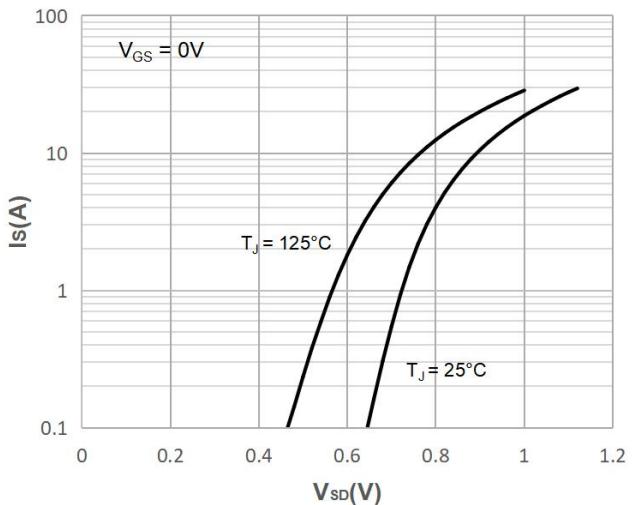
**Figure 2: Typical Transfer Characteristics**



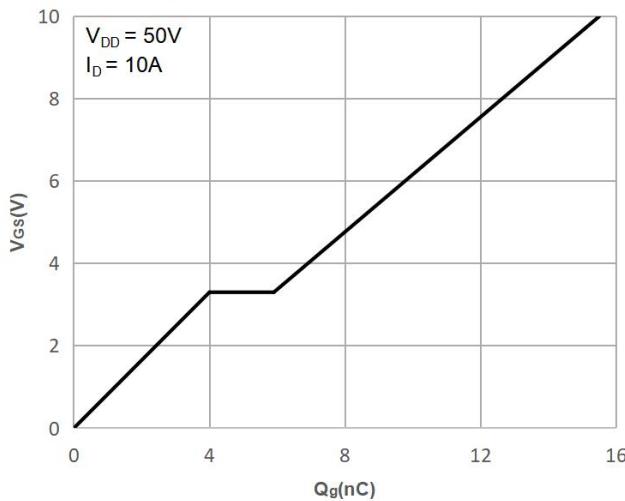
**Figure 3: On-resistance vs. Drain Current**



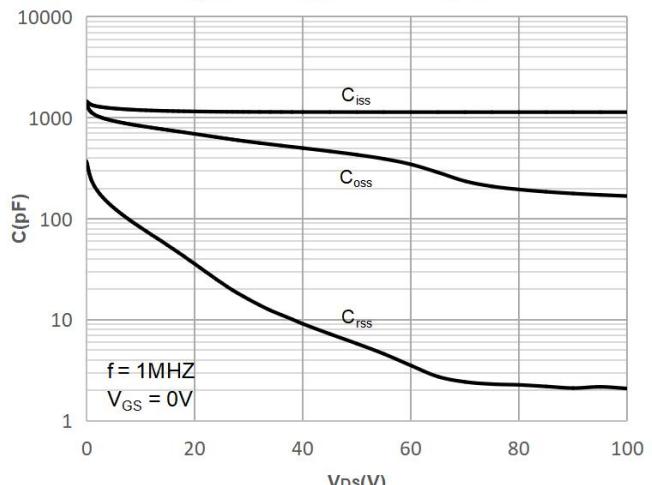
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

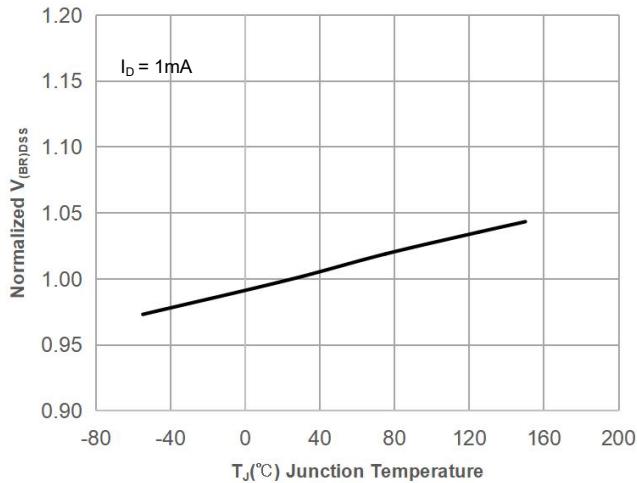


**Figure 6: Capacitance Characteristics**

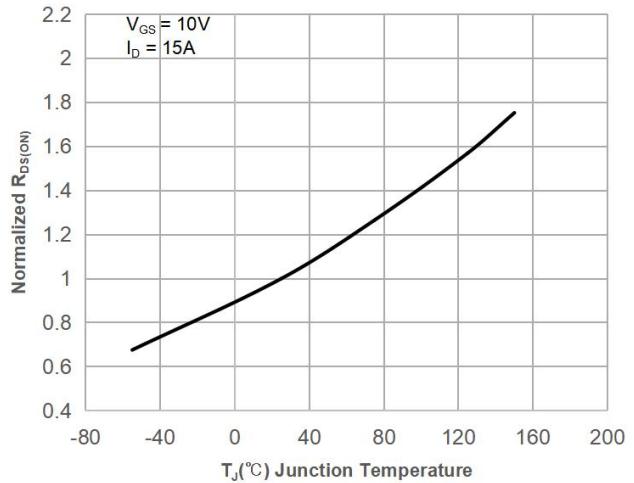


## Typical Characteristics

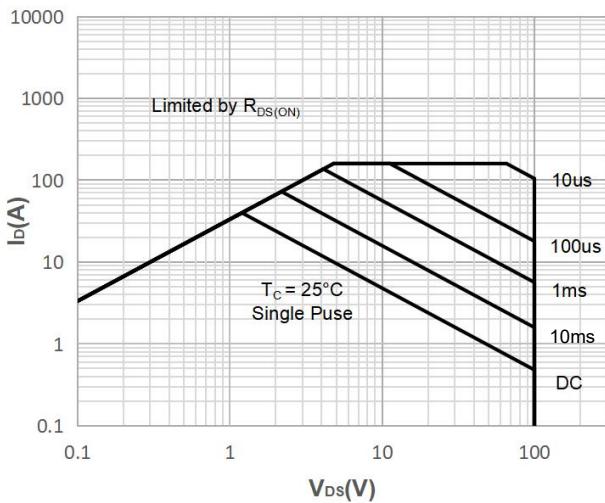
**Figure 7: Normalized Breakdown voltage vs. Junction Temperature**



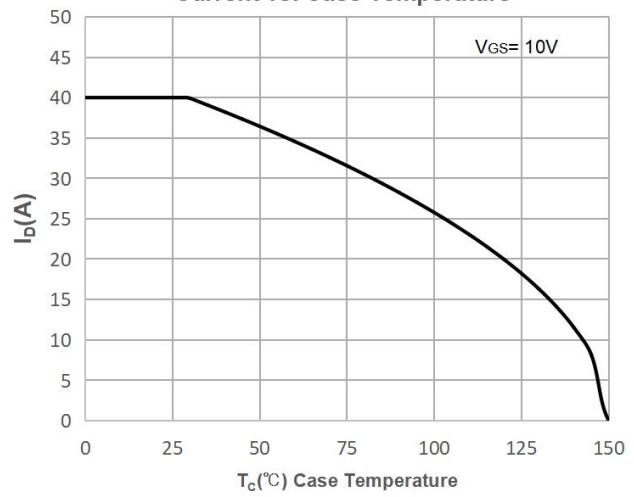
**Figure 8: Normalized on Resistance vs. Junction Temperature**



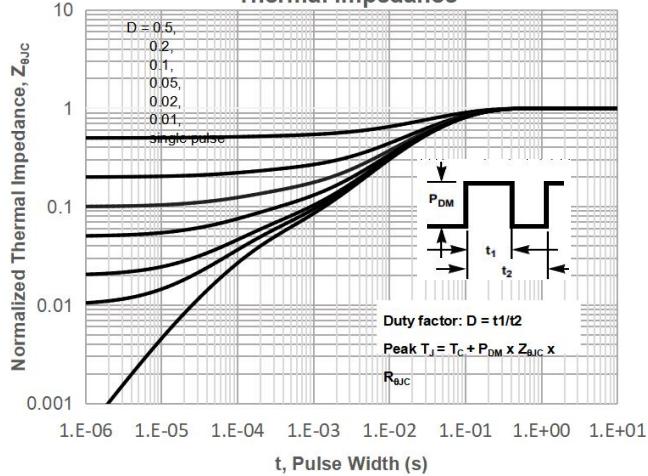
**Figure 9: Maximum Safe Operating Area**



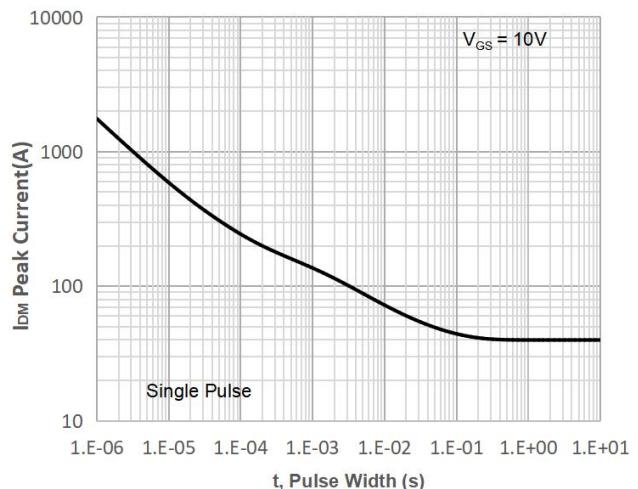
**Figure 10: Maximum Continuous Drain Current vs. Case Temperature**



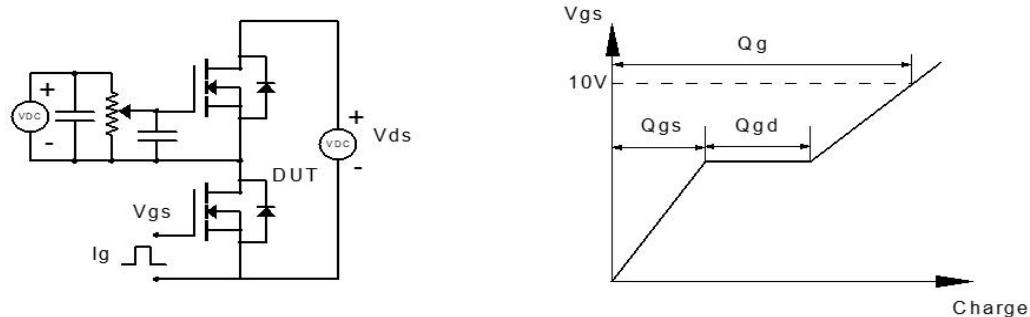
**Figure 11: Normalized Maximum Transient Thermal Impedance**



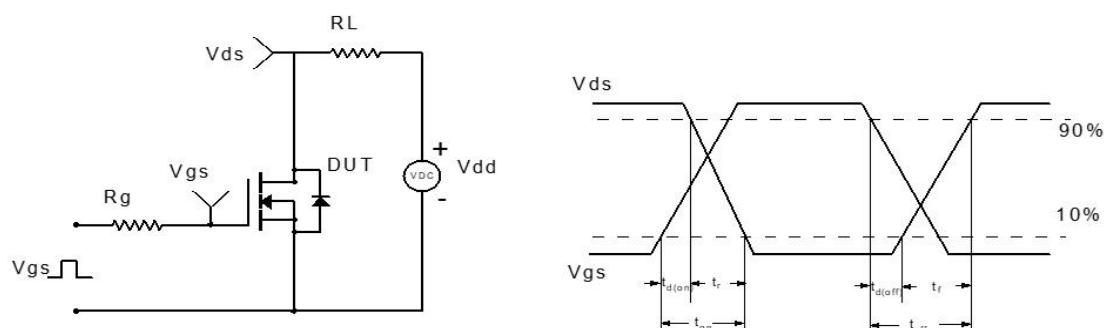
**Figure 12: Peak Current Capacity**



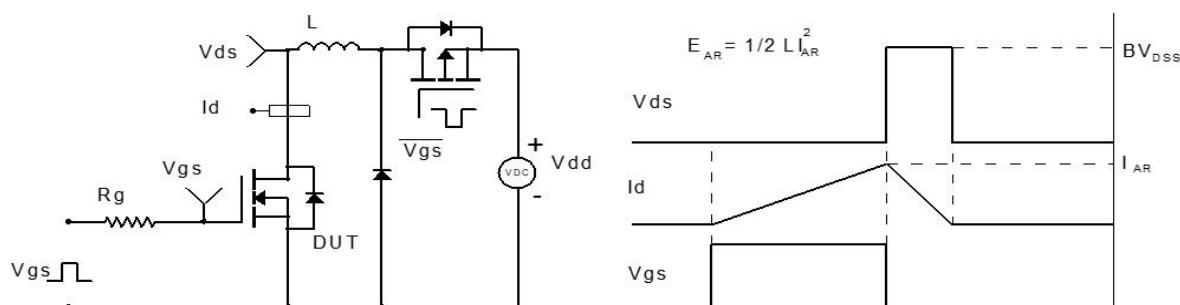
## Test Circuit



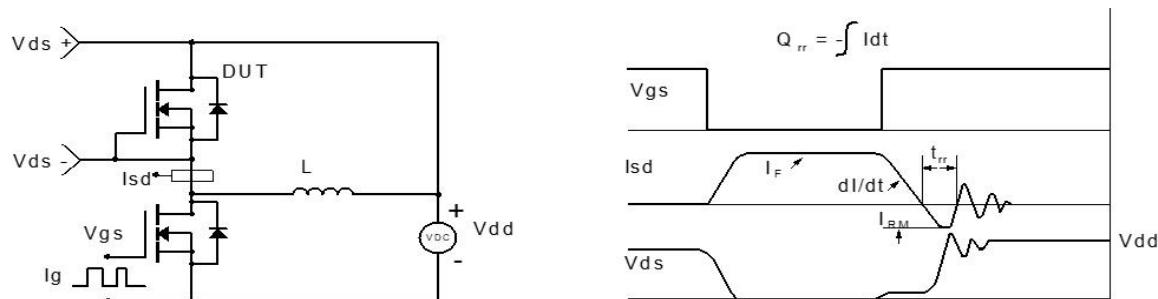
**Figure 1: Gate Charge Test Circuit & Waveform**



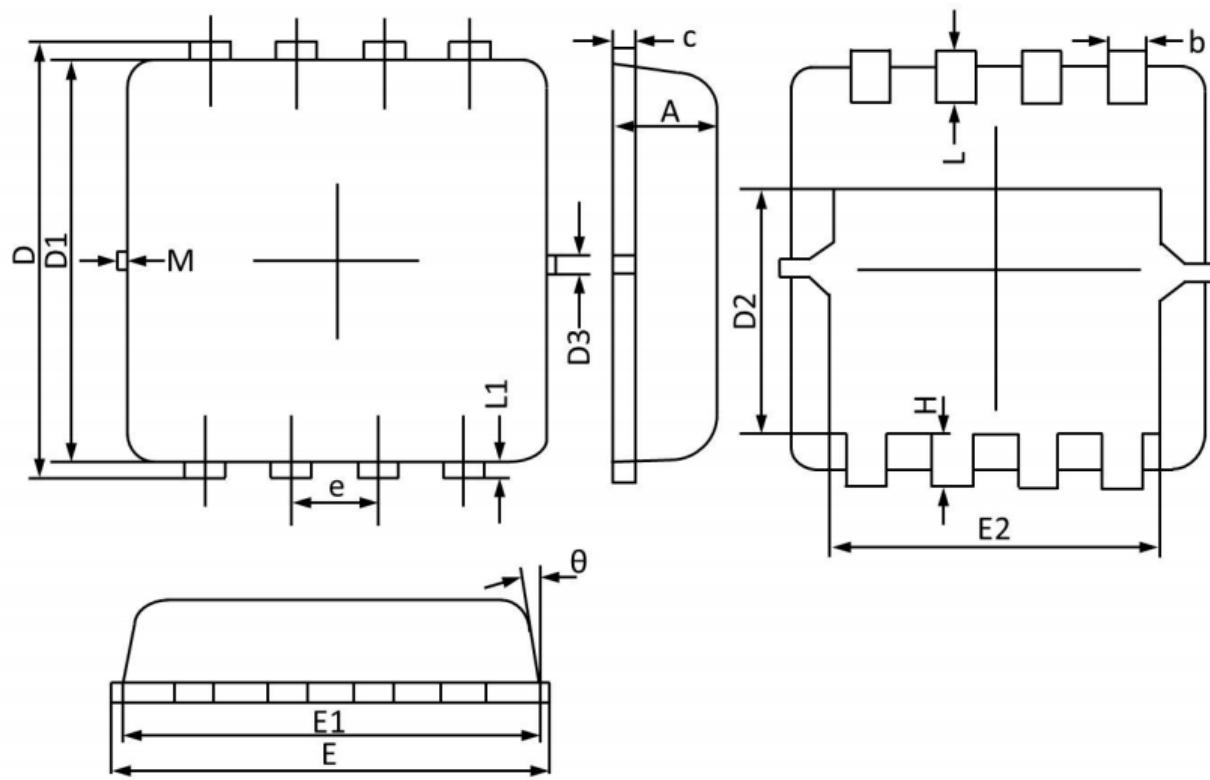
**Figure 2: Resistive Switching Test Circuit & Waveform**



**Figure 3: Unclamped Inductive Switching Test Circuit & Waveform**



**Figure 4: Diode Recovery Test Circuit & Waveform**

**PDFN3X3-8L Package Information (unit:mm)**

**DIMENSIONS**

<b>Symbol</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>	<b>Symbol</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>
<b>A</b>	0.70	0.75	0.80	<b>b</b>	0.25	0.30	0.35
<b>C</b>	0.10	0.15	0.25	<b>D</b>	3.25	3.35	3.45
<b>D1</b>	3.00	3.10	3.20	<b>D2</b>	1.78	1.88	1.98
<b>D3</b>	--	0.13	--	<b>E</b>	3.20	3.30	3.40
<b>E1</b>	3.00	3.15	3.20	<b>E2</b>	2.39	2.49	2.59
<b>e</b>	0.65BSC			<b>H</b>	0.30	0.39	0.50
<b>L</b>	0.30	0.40	0.50	<b>L1</b>	--	0.13	--
<b>θ</b>	--	10°	12°	<b>M</b>	*	*	0.15